

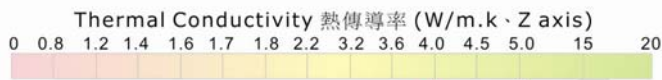
X889 Thermal Composite Materials

Feature 特性

- Good heat spreader 高散熱性
- Good thermal conductivity 高熱傳導性
- Easy to assemble 容易施工
- High stability 高穩定性

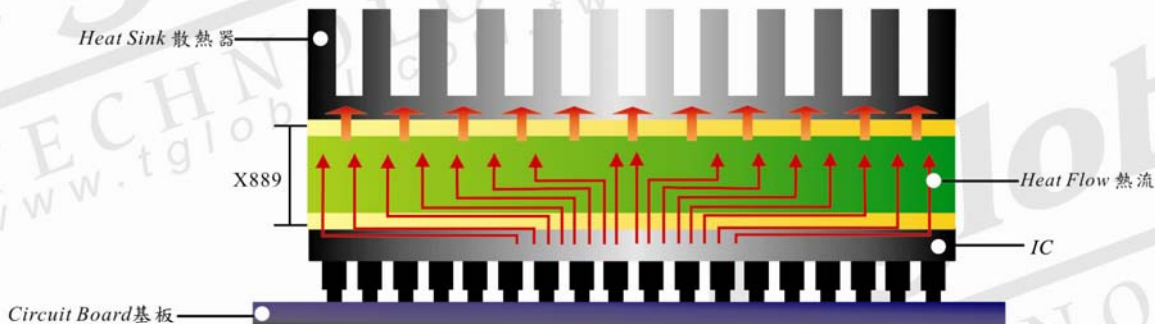
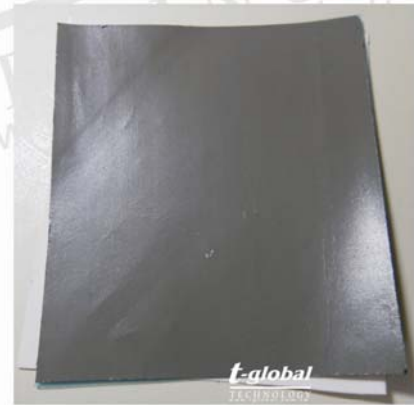
Application 產品應用端

- Electronic components: IC、CPU、MOS LED、M/B、P/S、Heat Sink.
- LCD-TV、Notebook PC、PC、Telecom Device、Wireless Hub..... etc.
- DDR II Module、DVD Applications、Hand-set applications.....etc.



Thermal Conductivity Z,5 W/m.k
X889

Thermal Conductivity Z,4 W/m.k
X889-1



Property	X889	X889-1	Unit	Test
	3 Layers (3層) Thermal silicone + Graphite + Thermal silicone	3 Layers (3層) Thermal silicone + AL + Thermal silicone		
Color 顏色	Gray 灰	Gray 灰	-	Visual
Thickness 厚度	0.25~0.6	0.13	mm 公厘	ASTM D374
	0.0098~0.0236	0.051	inch 公吋	ASTM D374
Thermal Conductivity 導熱係數	X-Y, 400	Z,4	W/m.k	ASTM D5470
	Z,5			
Flame Rating 耐燃等級	V-0	V-0	-	UL 94
Insulation Strength 耐電壓值	>1	>2	kv	ASTM D149
Weight Loss 重量損失	<1	<1	%	ASTM E595
Specific Gravity 比重	1.85	1.85	g/cm ³	ASTM D792
Working Temperature 工作溫度	-40~200	-40~200	°C	-
Volume Resistance 體積阻抗	2.2x10 ¹²	2.2x10 ¹²	ohm-cm	ASTM D257
REACH Compliant 符合REACH 規範	Yes 是	RoHS Compliant 符合RoHS 規範		Yes 是

● Pre-cut for different shape 可依需求沖型裁切

● Need sample? 樣品需求

